

Application No. 10/674209
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Amendment
Attorney Docket No. O11.2B-11333-US01

Recitation of the Claims:

1. **(Previously Presented)** A polishing composition used in a polishing process for reducing haze level of wafer surface, comprising:
hydroxyethyl cellulose compounded in said composition in a quantity of 0.01% to 3% by weight and having an average molecular weight in the range of 300,000 to 3,000,000;
polyethylene oxide compounded in said composition in a quantity larger than 0.005% by weight and smaller than 0.5% by weight and having an average molecular weight in the range of 30,000 to 50,000,000 ;
an alkaline compound;
water; and
silicon dioxide.
2. **(Original)** The polishing composition according to claim 1, wherein the total content of iron, nickel, copper, and calcium in the silicon dioxide, as measured in a 20 wt-% aqueous solution of said silicon dioxide, is 300 ppm or less.
3. **(Original)** The polishing composition according to claim 1, wherein the content of hydroxyethyl cellulose in the polishing composition is 0.1 to 1% by weight.
4. **(Original)** The polishing composition according to claim 1, wherein the content of silicon dioxide in the polishing composition is 3 to 20% by weight.
5. **(Original)** The polishing composition according to claim 1, wherein the alkaline compound is ammonia.